

DIELECTRIC COMPOSITION FOR FORMING DIELECTRIC LAYER FOR USE IN CIRCUITIZED SUBSTRATES

Abstract Of The Disclosure

A dielectric composition which forms a dielectric layer usable in circuitized substrates such as PCBs, chip carriers and the like. As such a layer, it includes a cured resin material and a predetermined percentage by weight of particulate fillers, thus not including continuous fibers, semi-continuous fibers or the like as part thereof.